

Heat resistant imide base material masking · tape for fixing semiconductor chip

272

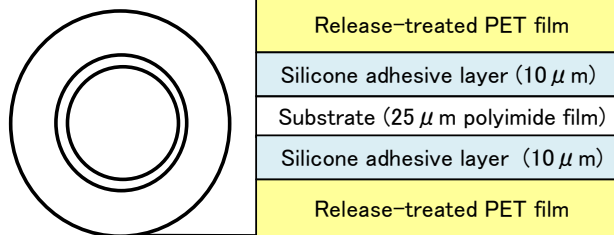
Feature

- ① Double-sided tape based on polyimide film
- ② Solder heat resistant
- ② Excellent adhesive residue to glass and semiconductor.

Use

Glass for C-MOS camera module, Masking tape for C-MOS

Construction



Characteristic

product name	Thickness (mm)	Base material (mm)	Adhesive force (N/25mm)	
			Light-release surface	Heavy-release surface
272	0.045	0.025	8	7

Measurement condition Tensile rate 300mm/min
 (Conforming to JIS Z 0237) Tension angle 180 degree: After bonding, the measured value after 1 hour
 Measurement temperature 23°C Adherend Stainless steel plate

Precautions on use

- All technical data are prepared based on tests and measured values conducted at the laboratory of KGK Chemical Co., Ltd. However, product characteristics may vary greatly depending on environment and adherend. Therefore, regarding these characteristic data, it is a reference value, not a guaranteed value. Before using it please make sure that this product is suitable for the intended use and environment.
- The above measurement is performed at room temperature (23 ° C).

Caution on storage

- Please be sure to put it in a box and keep it.
 - Please choose a cold and dark place not to be exposed to direct sunlight for the storage location.
- In particular, please do not expose to high temperature and high humidity
 (temperature 30 °C or more and humidity 50% or more forbidden).

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